

What is claimed is:

1. A semiconductor package, comprising:

an electrically conductive member having a spherical terminal;

a semiconductor chip which is electrically connected to said electrically

5 conductive members; and

a sealing member for sealing said electrically conductive members and said semiconductor chip therein;

wherein a part of said spherical terminal is exposed from said sealing member, and said spherical terminal is electrically connected to said electrically
10 conductive member via a protrusion formed on said electrically conductive member.

2. A semiconductor package according to claim 1, wherein the electrically
15 conductive members are leads of a lead frame.

3. A semiconductor package according to claim 2, wherein the protrusion
has an extremity forming an acute angle.

4. A semiconductor package according to claim 3, wherein the protrusion
20 has a height in size equivalent to about 10 to 50% of the diameter of the spherical

terminal.

5. A semiconductor package according to claim 4, wherein the protrusion is caused to pierce the spherical terminal when a press-down force acts between the spherical terminal and the leads.

6. A semiconductor package according to claim 2, wherein the protrusion has an extremity provided with a rough face.

7. A semiconductor package according to claim 6, wherein the protrusion is made up of a plated face.

8. A semiconductor package according to claim 7, wherein the protrusion is connected to the spherical terminal when a press-down force acts between the spherical terminal and the leads.

9. A method of fabricating a semiconductor package comprising:

a step of preparing a lead frame provided with a protrusion;

a step of preparing a first molding die member having a cavity;

a step of preparing a second molding die member to be engaged with the

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spherical terminal via the rough face in the step of holding the lead frame between the first and second molding die members.

13. A method of fabricating a semiconductor package according to claim 9,
5 further comprising a step of sucking in the spherical terminal via a through hole defined in the bottom of the cavity of the first molding die member.

14. A method of forming a semiconductor package which comprises the steps of:

preparing a lead frame having a spherical terminal;

preparing a first mold die having a cavity with a through hole in the bottom thereof;

preparing a second mold die for matching with said first molding die;

placing said lead frame between said first and second mold dies, wherein

15 said spherical terminal of said lead frame is placed in said cavity;

absorbing air existing between said spherical terminal and said bottom of said cavity via said through hole for contacting said spherical terminal with the inner side of said cavity; and

injecting a molding composition between said first and second mold dies.

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15. A method of forming a semiconductor package which comprises the steps of:

preparing a lead frame having a spherical terminal;

preparing a first mold die having a cavity with a through hole in the bottom

5 thereof;

preparing a second mold die for matching with said first molding die;

placing said lead frame between said first and second mold dies, wherein

said spherical terminal of said lead frame is placed in said cavity;

pressing down said second mold die for tightly contacting said spherical

10 terminal with the inner side of said cavity; and

injecting a molding composition between said first and second mold dies.

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